

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of claims:**

Claims 1-5 (canceled).

Claim 6 (new):           A method for the production of circuit boards comprising the steps of:  
drilling through-bores for establishing through-connections;  
through-connecting, wherein an electrically conductive general layer is built up;  
etching a strip conductor image into the electrically conductive general layer;  
filling of the bores of the through-connections with a medium;  
lacquering of the surfaces on which through-connections are present and, at least in the proximity of which, strip conductors are later provided;  
applying an insulating lacquer to the surfaces of the circuit board; and  
producing strip conductors arranged above the through-connections.

Claim 7 (new):           The method as claimed in claim 6, wherein the medium used in filling the bores and insulating lacquer is identical.

Claim 8 (new):           The method as claimed in claim 6, wherein the medium used in filling the bores and the insulating lacquer is a low cost lacquer variant.

Claim 9 (new):           The method as claimed in claim 6 wherein the strip conductors arranged above the through-connections are carbon.

Claim 10 (new):          The method as claimed in claim 6, further comprising separating individual circuit boards by means of a milling process.

Claim 11 (new): The method as claimed in claim 6, wherein the through-bores are 20  $\mu\text{m}$  in size.

Claim 12 (new): The method as claimed in claim 6, wherein the insulating lacquer is an 150 lacquer.